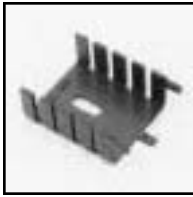


BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



286 SERIES Aluminum and Copper Low-Cost Wave-Solderable Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Material	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
286-AB ▲	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Aluminum, Anodized	58°C @ 4W	7.4°C/W @ 200 LFM	0.0085 (3.86)
286-CBT ▲	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Black	58°C @ 4W	7.4°C/W @ 200 LFM	0.0250 (11.34)
286-CT	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Tinned	58°C @ 4W	7.4°C/W @ 200 LFM	0.0250 (11.34)

Efficient heat removal at low cost can be achieved by inserting the 286 Series directly into pre-drilled circuit boards; scored mounting tabs may be bent after insertion to provide added stability.

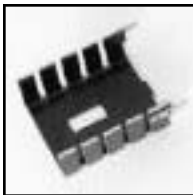
The 286 Series can be wavesoldered directly to the board. Material: 286-AB style (aluminum, black anodized), 286-CBT style (copper, black paint tin tabs), and 286-CT style (copper, tinned).

MECHANICAL DIMENSIONS

Dimensions: in. (mm)

286 SERIES

NATURAL AND FORCED CONVECTION CHARACTERISTICS



287 SERIES Wave-Solderable Low-Cost Heat Sinks

TO-220

Standard P/N	Mounting Slot	Mounting Hole	Height Above PC Board in. (mm)	Maximum Footprint "A" in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
					Natural Convection	Forced Convection	
287-1AB ▲	287-1ABH ▲	287-1ABH ▲	1.180 (30.0)	1.000 (25.4) x 0.500 (12.7)	65°C @ 4W	7.8°C/W @ 200 LFM	0.0090 (4.08)
287-2AB ▲	287-2ABH	287-2ABH	1.180 (30.0)	1.000 (25.4) x 1.000 (25.4)	55°10 @ 4W	6.4°C/W @ 200 LFM	0.0140 (6.35)

Material: Aluminum, Black Anodized

Mount these cost-effective TO-220 heat sinks vertically into pre-drilled printed circuit boards. Soldered, pre-tinned tabs can be wavesoldered directly to the board. A 0.375 in. (9.5 mm)

mounting slot allows for correct positioning of TO-220 and similar semiconductor packages.

MECHANICAL DIMENSIONS

Dimensions: in. (mm)

287 SERIES

NATURAL AND FORCED CONVECTION CHARACTERISTICS



695 SERIES Space-Saving Heat Sinks for Small Stud-Mounted Diodes

STUD-MOUNT

Standard P/N	Maximum Width in. (mm)	Height in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
695-1B ▲	1.330 (33.8)	0.530 (13.7)	72°C @ 4.0W	5.2°C/W @ 400 LFM	0.0030 (1.36)

Mount and effectively heat sink small stud-mounted diodes with the 695 Series space-saving heat sink type. Each unit is black anodized aluminum with an 0.200 in. (5.1) dia. mounting hole centered in the base. The folded fin design

provides good heat dissipation for use where height is limited above the printed circuit board or base plate.

MECHANICAL DIMENSIONS

Dimensions: in. (mm)

695 SERIES

NATURAL AND FORCED CONVECTION CHARACTERISTICS